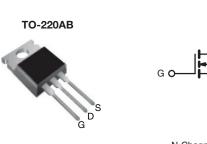
## SiHP12N60E





## **E Series Power MOSFET**

PRODUCT SUMMARY				
V <sub>DS</sub> (V) at T <sub>J</sub> max.	650			
R <sub>DS(on)</sub> max. at 25 °C (Ω)	V <sub>GS</sub> = 10 V 0.38			
Q <sub>g</sub> max. (nC)	58			
Q <sub>gs</sub> (nC)	6			
Q <sub>gd</sub> (nC)	13			
Configuration	Single			



S

N-Channel MOSFET

### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q<sub>q</sub>)
- Avalanche energy rated (UIS)
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

### **APPLICATIONS**

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Renewable energy
  - Solar (PV inverters)

ORDERING INFORMATION				
Package	TO-220AB			
Lead (Pb)-free	SiHP12N60E-E3			
Lead (Pb)-free and Halogen-free	SiHP12N60E-GE3			

<b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_c = 25 \degree C$ , unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V <sub>DS</sub>	600	V	
Gate-Source Voltage			V <sub>GS</sub>	± 30	V	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	$T_{\rm C} = 25 \ ^{\circ}{\rm C}$ $T_{\rm C} = 100 \ ^{\circ}{\rm C}$	- I <sub>D</sub>	12		
	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C		7.8	А	
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	27		
Linear Derating Factor				1.2	W/°C	
Single Pulse Avalanche Energy <sup>b</sup>			E <sub>AS</sub>	117	mJ	
Maximum Power Dissipation			PD	147	W	
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-Source Voltage Slope	T <sub>J</sub> = 125 °C		-l) / / -l+	70		
Reverse Diode dV/dt d			dV/dt	5	V/ns	
Soldering Recommendations (Peak Temperature) c for 10 s				300	°C	

#### Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b.  $V_{DD} = 50$  V, starting  $T_J = 25$  °C, L = 11.6 mH,  $R_g = 25 \Omega$ ,  $I_{AS} = 4.5$  A.

c. 1.6 mm from case. d.  $I_{SD} \le I_D$ , dl/dt = 100 A/µs, starting  $T_J = 25$  °C.

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FREE

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PARAMETER	SYMBOL	TYP.	MAX	MAX.		UNIT		
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	62			00.004		
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	- 0.85			- °C/W			
<b>SPECIFICATIONS</b> ( $T_J = 25 \degree C$ ,	unless otherw	ise noted)						
PARAMETER	SYMBOL	1	CONDITIONS	MIN.	TYP.	MAX.		
Static								
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> :	= 0 V, I <sub>D</sub> = 250 μΑ	600	-	-	V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$		e to 25 °C, I <sub>D</sub> = 1 mA	-	0.71	-	V/°C	
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2	-	4	V	
			$V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA	
Gate-Source Leakage	I <sub>GSS</sub>		$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μA	
Zana Oata Malta na Duain Ourread		V <sub>DS</sub> =	= 600 V, V <sub>GS</sub> = 0 V	-	-	1		
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = 480 V	′, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	10	μA	
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	$V_{GS} = 10 V$	I <sub>D</sub> = 6 A	-	0.32	0.38	Ω	
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub>	= 40 V, I <sub>D</sub> = 8 A	-	3.8	-	S	
Dynamic	*			•	•	•	•	
Input Capacitance	C <sub>iss</sub>		V <sub>GS</sub> = 0 V,		937	-		
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 0.0$ V, $V_{DS} = 100$ V, f = 1 MHz		-	53	-		
Reverse Transfer Capacitance	C <sub>rss</sub>			-	5	-		
Effective Output Capacitance, Energy Related <sup>a</sup>	C <sub>o(er)</sub>	$V_{DS}$ = 0 V to 480 V, $V_{GS}$ = 0 V		-	41	-	pF	
Effective Output Capacitance, Time Related <sup>b</sup>	C <sub>o(tr)</sub>			-	136	-		
Total Gate Charge	Qg				29	58	nC	
Gate-Source Charge	Q <sub>gs</sub>	$V_{GS} = 10 \text{ V}$ $I_D = 6 \text{ A}, V_{DS} = 480 \text{ V}$		-	6	-		
Gate-Drain Charge	Q <sub>gd</sub>			-	13	-	1	
Turn-On Delay Time	t <sub>d(on)</sub>			-	14	28		
Rise Time	t <sub>r</sub>	Voo	= 480 V, I <sub>D</sub> = 6 A,	-	19	38	ns	
Turn-Off Delay Time	t <sub>d(off)</sub>		$= 10 \text{ V}, \text{ R}_{g} = 9.1 \Omega$	-	35	70		
Fall Time	t <sub>f</sub>			-	19	38		
Gate Input Resistance	R <sub>g</sub>	f = 1 MHz, open drain		-	1.1	-	Ω	
Drain-Source Body Diode Characterist	ics							
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	12	^	
Pulsed Diode Forward Current	I <sub>SM</sub>			-	-	48	A	
Diode Forward Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °	$T_{J} = 25 \text{ °C}, I_{S} = 6 \text{ A}, V_{GS} = 0 \text{ V}$		-	1.2	V	
Reverse Recovery Time	t <sub>rr</sub>			-	350	-	ns	
Reverse Recovery Charge	Q <sub>rr</sub>	$T_J = 25 \text{ °C}, I_F = I_S = 6 \text{ A},$ dI/dt = 100 A/µs, V <sub>R</sub> = 25 V		-	4	-	μC	
Reverse Recovery Current	I <sub>RRM</sub>			-	19		A	

#### Notes

a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .

b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .



# SiHP12N60E

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### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

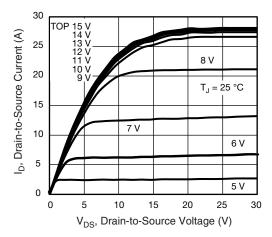


Fig. 1 - Typical Output Characteristics

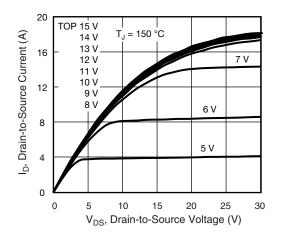


Fig. 2 - Typical Output Characteristics

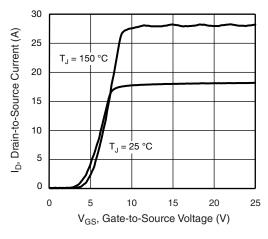


Fig. 3 - Typical Transfer Characteristics

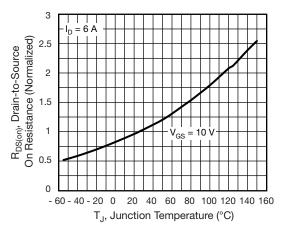


Fig. 4 - Normalized On-Resistance vs. Temperature

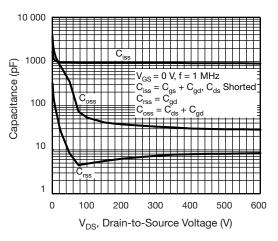


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

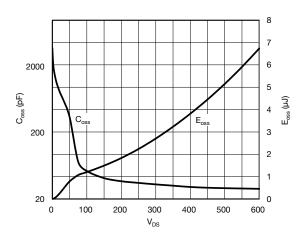


Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$ 

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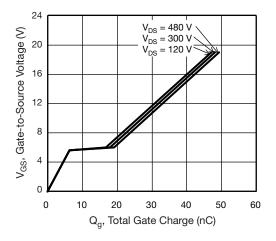


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

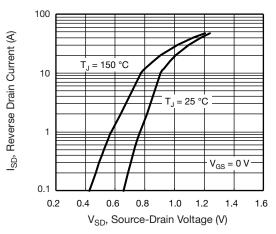


Fig. 8 - Typical Source-Drain Diode Forward Voltage

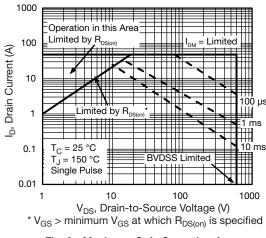


Fig. 9 - Maximum Safe Operating Area

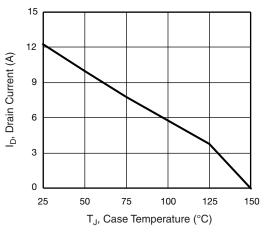


Fig. 10 - Maximum Drain Current vs. Case Temperature

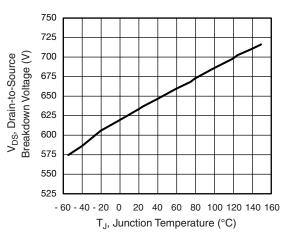
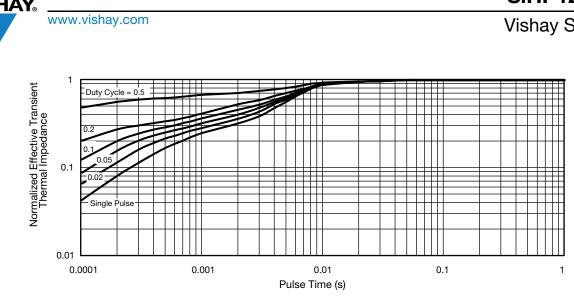


Fig. 11 - Temperature vs. Drain-to-Source Voltage





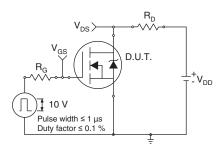


Fig. 13 - Switching Time Test Circuit

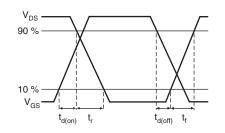
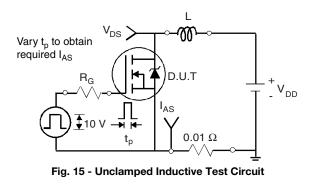


Fig. 14 - Switching Time Waveforms



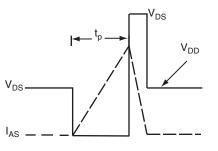


Fig. 16 - Unclamped Inductive Waveforms

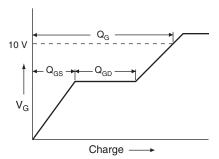


Fig. 17 - Basic Gate Charge Waveform

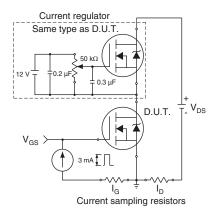


Fig. 18 - Gate Charge Test Circuit

S15-0277-Rev. D, 23-Feb-15

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#### Peak Diode Recovery dV/dt Test Circuit

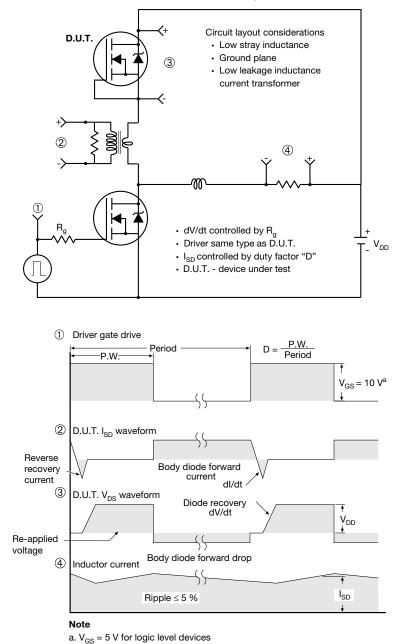


Fig. 19 - For N-Channel

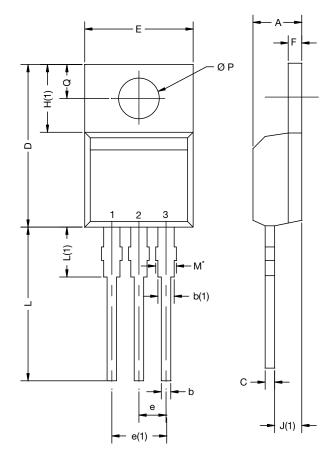
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**TO-220-1** 



DIM.	MILLIN	IETERS	INCHES		
DIIVI.	MIN.	MAX.	MIN.	MAX.	
А	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
Е	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØΡ	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031					

Note

•  $M^* = 0.052$  inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM

Package Picture					
ASE		Xi'an			
		IRF 9510 744K AB			

Revison: 14-Dec-15

Document Number: 66542

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